3EC-M3-VLP

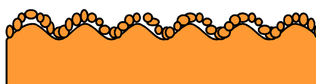
MITSUI KINZOKU

- 极低粗糙度铜箔，适用于细线路蚀刻之减成法制程。
  Low profile copper foil, suitable for fine etching in the substractive process.
- 高抗张力，于薄铜箔易于操作。
  High tensile strength, easy to handle thin foil.
- 最薄之7μm铜箔具量产能力。
  From 7μm, we line up.

用途/Application

- IC封装载板
  /Semiconductor Package
- 高密度互连技术板
  /High Density Interconect
- 软性电路板
  /Flexible Print Board

构成/Composition



生产地点/Production Site

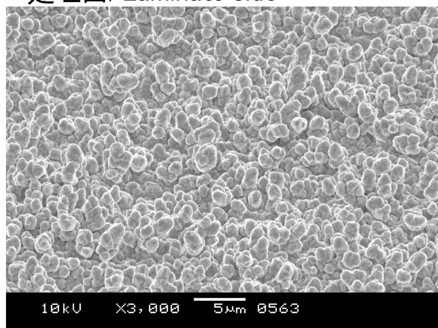
- 日本 / Japan

代表性特性数据/Representive date

	μm	Area weight (g/m2)	Laminate side Rz(μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)@FR-4
3EC-M3-VLP	9	80	2.8	500	4	0.9
	12	107	3.0	500	5	1.2
	18	153	3.5	500	8	1.4

※上述表列为代表性数据非保证值。
This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/ resist side